

Recommended Application

Peripheral Clock for Intel Servers with Wake-On-Lan support

Output Features

- 1 - 0.7V current-mode differential CPU pair
- 6 - 50MHz RMI2 outputs
- 2- 125MHz RGMII outputs
- 1 - 0.7V current-mode differential DOT 96MHz output
- 1 - 33.33MHz output
- 1 - 32.768KHz output
- 2 - 25MHz REF outputs

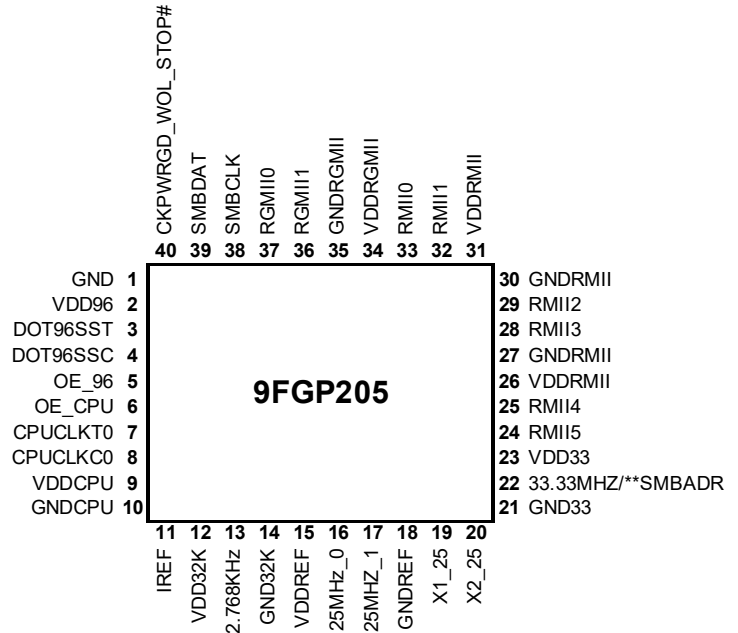
Key Specifications

- Exact synthesis on CPU, RMI2, RGMII and 33.33MHz clocks
- ±100ppm frequency accuracy on remaining clocks

Features/Benefits

- Selectable SMBus Address - D0/D1 or C0/C1
- Spread Spectrum capability on CPU and DOT 96MHz clocks
- In WOL_STOP# mode, Pin 16, 29, 32 and 33 default to ON
- SMBus Control:
 - M/N and spread programming on CPU and DOT 96MHz clocks via SMBus
 - Differential outputs can be disabled via pins or SMBus

Pin Configuration



40-pin VQFPN
* Internal Pull-Up Resistor
** Internal Pull-Down Resistor

Functionality

CPU FS2	CPU FS1	CPU FS0	CPUCLK	DOT96SS	33.33	RMI2	RGMII	25	32.768
Byte0 Bit2	Trays	Byte0 Bit0	MHz	MHz	MHz	MHz	MHz	MHz	KHz
0	0	0	266.67	96.00	33.33	50.00	125.00	25.00	32.768
0	0	1	133.33	96.00	33.33	50.00	125.00	25.00	32.768
0	1	0	200.00	96.00	33.33	50.00	125.00	25.00	32.768
0	1	1	166.67	96.00	33.33	50.00	125.00	25.00	32.768
1	0	0	333.33	96.00	33.33	50.00	125.00	25.00	32.768
1	0	1	100.00	96.00	33.33	50.00	125.00	25.00	32.768
1	1	0	400.00	96.00	33.33	50.00	125.00	25.00	32.768
1	1	1	Reserved	96.00	33.33	50.00	125.00	25.00	32.768

Power up default is highlighted.

SMBus Address Selection

SMBADR	
*SMBADR = 0	SMBADR = 1
D0/D1	C0/C1

* Default value

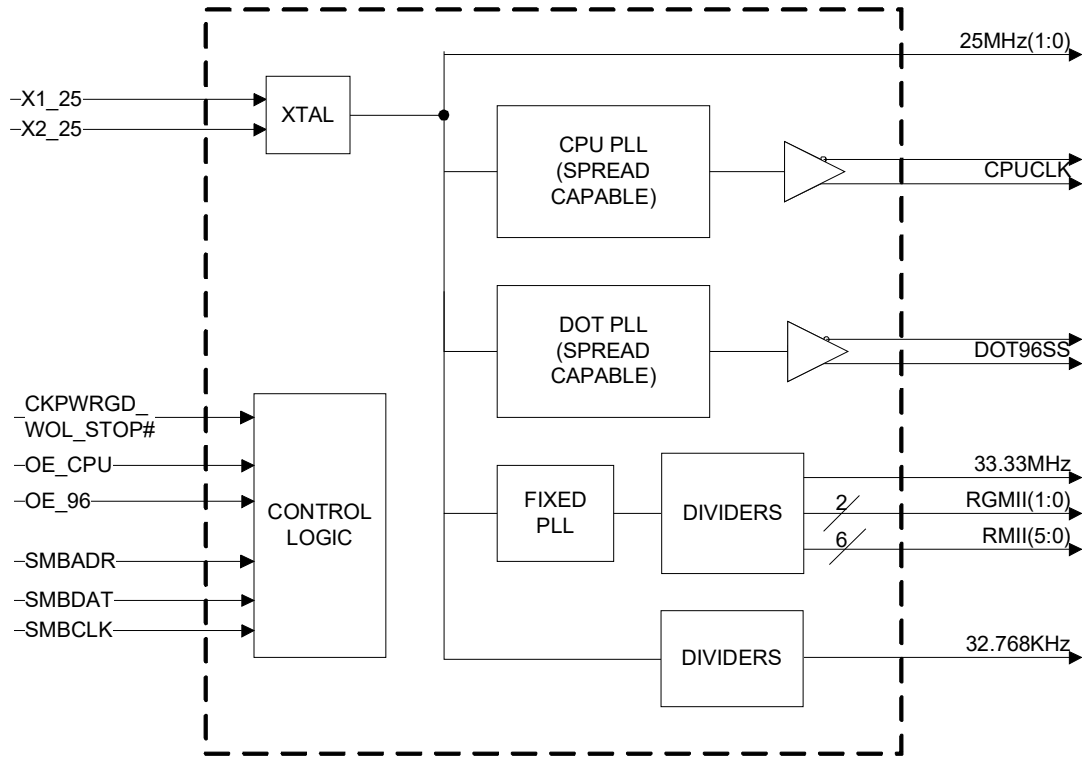
Pin Descriptions

PIN #	PIN NAME	PIN TYPE	DESCRIPTION
1	GND	PWR	Ground pin.
2	VDD96	PWR	Power pin for the DOT96 clocks, nominal 3.3V
3	DOT96SST	Trays	True clock of differential pair for 96.00MHz spread spectrum capable DOT clock. These are current mode outputs. External resistors are required for voltage bias.
4	DOT96SSC	OUT	Complementary clock of differential pair for 96.00MHz spread spectrum capable DOT clock. These are current mode outputs. External resistors are required for voltage bias.
5	OE_96	IN	Active high input for enabling 96Hz outputs. 1 = enable output(s), 0 =disable output(s)
6	OE_CPU	IN	Active high input for enabling CPU DIFF pairs. 1 = enable output(s), 0 =disable output(s)
7	CPUCLKT0	OUT	True clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
8	CPUCLKC0	OUT	Complementary clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
9	VDDCPU	PWR	Supply for CPU clocks, 3.3V nominal
10	GNDCPU	PWR	Ground pin for the CPU outputs
11	IREF	OUT	This pin establishes the reference for the differential current-mode output pairs. It requires a fixed precision resistor to ground. 475ohm is the standard value for 100ohm differential impedance. Other impedances require different values. See data sheet.
12	VDD32K	PWR	Power pin for the 32.768KHz outputs, nominal 3.3V
13	32.768KHz	OUT	32.768KHz clock output
14	GND32K	PWR	Ground pin for the 32.768KHz outputs
15	VDDREF	PWR	Ref, XTAL power supply, nominal 3.3V
16	25MHz_0	OUT	25MHz clock output, 3.3V
17	25MHz_1	OUT	25MHz clock output, 3.3V
18	GNDREF	PWR	Ground pin for the REF outputs.
19	X1_25	IN	Crystal input, Nominally 25.00MHz.
20	X2_25	OUT	Crystal output.
21	GND33	PWR	Ground pin for the 33.33MHz outputs
22	33.33MHz/**SMBADR	I/O	33.33MHz clock output / SMBus address select bit.
23	VDD33	PWR	Power pin for the 33.33MHz outputs, nominal 3.3V
24	RMII5	OUT	3.3V 50MHz RMII clock output
25	RMII4	OUT	3.3V 50MHz RMII clock output
26	VDDRMII	PWR	3.3V power pin for the RMII clocks.
27	GNDRMII	PWR	Ground pin for the RMII outputs
28	RMII3	OUT	3.3V 50MHz RMII clock output
29	RMII2	OUT	3.3V 50MHz RMII clock output
30	GNDRMII	PWR	Ground pin for the RMII outputs
31	VDDRMII	PWR	3.3V power pin for the RMII clocks.
32	RMII1	OUT	3.3V 50MHz RMII clock output
33	RMII0	OUT	3.3V 50MHz RMII clock output
34	VDDRGMII	PWR	3.3V power pin for the RGMII clocks and PLL
35	GNDRGMII	PWR	Ground pin for the RGMII outputs
36	RGMII1	OUT	3.3V 125MHz RGMII clock output
37	RGMII0	OUT	3.3V 125MHz RGMII clock output
38	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
39	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
40	CKPWRGD_WOL_STOP#	IN	Notifies clock to sample latched inputs on first low to high transition. After first power up, a low stops all outputs except those designated to run in power down mode (WOL_STOP# mode)

General Description

The 9FGP205 is a peripheral clock for Intel Servers. It is driven with a 25MHz crystal and generates a variety of clocks, including 125MHz RGMII. An SMBus interface allows full control of the device.

Block Diagram

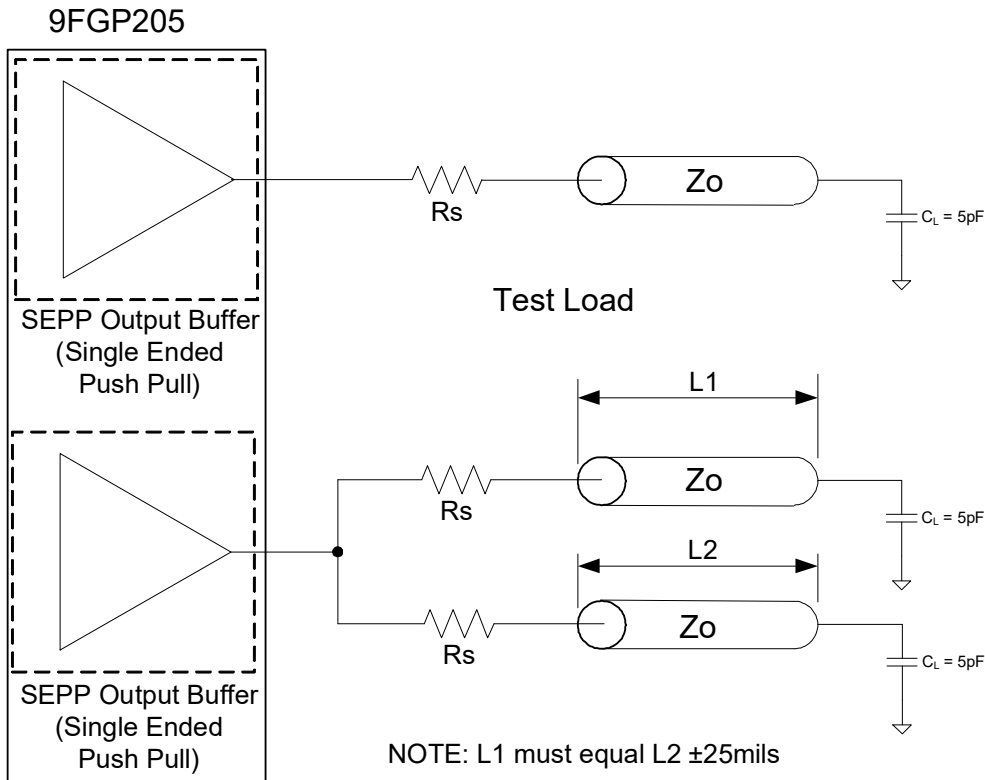


Power Supply Pins

Pin Number		Description
VDD	GND	
9	10	Trays
2	1	DOT96SS output and PLL
34	35	125 MHz RGMII outputs and PLL
26,31	27,30	50 MHz RMII outputs
23	21	33.33MHz output
12	14	32.768KHz output
15	18	XTAL, REF outputs

Note: All VDD should be connected to a common power rail with proper filtering and decoupling. Pins 2, 9 and 34 should be treated as analog pins for decoupling purposes.

Test Loads



Drive Strength for all the single-ended outputs can be controlled by the SMBus Bytes 4 and 5 as shown in the Default Drive Strength table.

Default Drive Strength Table

	Default Drive	Optional Drive
RGMII	1 Load	NA
RMII	1 Load	2 Loads
33.33MHz	2 Loads	1 Load
25Mhz	2 Loads	1 Load
32.768KHz	2 Loads	1 Load

Series Termination Resistor Values EXCEPT RGMII

Output Drive Strength	Series Resistor (Rs) for driving 1 Load	Series Resistor (Rs) for driving 2 Loads
1 Load	22 ohms	N/A
2 Loads	33 ohms	8.2 ohms

Note: All values are for $Z_o = 50\Omega$

Series Termination Resistor Values – RGMII

Output Drive Strength	Series Resistor (Rs) for driving 1 Load	Series Resistor (Rs) for driving 2 Loads
1 Load	27 ohms	N/A

Note: All values are for $Z_o = 50\Omega$

Truth Table 1: CKPWRGD_WOL_STOP#, OE_96 and OE_CPU

CKPWRGD_WOL_STOP#	OE_96	DOT96SSC	OE_CPU	CPUCLK
0	X	X	X	X
0				
1	0	Disabled	0	Disabled
1	1	Enabled	1	Enabled

*Assuming DOT96 Output Enable from SMBus Byte2 Bit0 set to enable (default)

*Assuming CPUCLK Output Enable from SMBus Byte2 Bit1 set to enable (default)

Truth Table 2: CKPWRGD_WOL_STOP# Single-ended outputs

CKPWRGD_WOL_STOP#	Pin 16, 29, 32, 33	Pin 22	Other outputs
0	Running	Hi-Z	Low
1	Running	Running	Running

*Assuming SMBus at default value.

Table 1: CPU Spread and Frequency Selection

CPU SS_EN	CPU FS2	CPU FS1	CPU FS0	CPU MHz	Down Spread %
Byte 0 Bit 3	Byte 0 Bit 2	Byte 0 Bit 1	Byte 0 Bit 0		
0	0	0	0	266.67	0%
0	0	0	1	133.33	0%
0	0	1	0	200.00	0%
0	0	1	1	166.67	0%
0	1	0	0	333.33	0%
0	1	0	1	100.00	0%
0	1	1	0	400.00	0%
0	1	1	1	200.00	0%
1	0	0	0	266.67	0.5%
1	0	0	1	133.33	0.5%
1	0	1	0	200.00	0.5%
1	0	1	1	166.67	0.5%
1	1	0	0	333.33	0.5%
1	1	0	1	100.00	0.5%
1	1	1	0	400.00	0.5%
1	1	1	1	200.00	0.5%

Table2: DOT96 Spread and Frequency Selection Table

DOT96 SS_EN	FS3	FS2	FS1	FS0	DOT96SS MHz	Spread %	
Byte 0 bit 4	Byte 3 bit 3	Byte 3 bit 2	Byte 3 bit 1	Byte 3 bit 0			
0	0	0	0	0	96.00	0	
0	0	0	0	1	96.00	0	
0	0	0	1	0	96.00	0	
0	0	0	1	1	96.00	0	
0	0	1	0	0	96.00	0	
0	0	1	0	1	96.00	0	
0	0	1	1	0	96.00	0	
0	0	1	1	1	96.00	0	
0	1	0	0	0	96.00	0	
0	1	0	0	1	96.00	0	
0	1	0	1	0	96.00	0	
0	1	0	1	1	96.00	0	
0	1	1	0	0	96.00	0	
0	1	1	0	1	96.00	0	
0	1	1	1	0	96.00	0	
0	1	1	1	1	96.00	0	
1	0	0	0	0	96.00	+/-0.25	Center
1	0	0	0	1	96.00	+/-0.5	Center
1	0	0	1	0	96.00	+/-0.75	Center
1	0	0	1	1	96.00	+/-1.0	Center
1	0	1	0	0	96.00	-0.25	Down
1	0	1	0	1	96.00	-0.50	Down
1	0	1	1	0	96.00	-0.75	Down
1	0	1	1	1	96.00	-1.0	Down
1	1	0	0	0	96.00	-1.25	Down
1	1	0	0	1	96.00	-1.50	Down
1	1	0	1	0	96.00	-1.75	Down
1	1	0	1	1	96.00	-2.0	Down
1	1	1	0	0	96.00	-2.25	Down
1	1	1	0	1	96.00	-2.5	Down
1	1	1	1	0	96.00	-2.75	Down
1	1	1	1	1	96.00	-3.00	Down

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9FGP205. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
3.3V Supply Voltage	VDDxxx	-	GND - 0.5	3.3V	GND + 4.5	V	1
Maximum difference across all VDD pins	VDDdelta	Trays			0.5	V	1
Storage Temperature	Ts	-	-65		150	°C	1
Ambient Operating Temp	Tambient	-	0		70	°C	1
Junction Temperature	Tj	-			125	°C	1
Input ESD protection HBM	ESD prot	-	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics–Input/Supply/Common Output Parameters

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	Notes
Input High Voltage	V_{IH}	3.3 V +/-5%	1.8		$V_{DD} + 0.3$	V	1
Input Low Voltage	V_{IL}	3.3 V +/-5%	$V_{SS} - 0.3$		1.4	V	1
Input High Current	I_{IH}	$V_{IN} = V_{DD}$	-5		5	uA	1
Input Low Current	I_{IL1}	$V_{IN} = 0$ V; Inputs with no pull-up resistors	-5			uA	1
	I_{IL2}	$V_{IN} = 0$ V; Inputs with pull-up resistors	-200			uA	1
Low Threshold Input-High Voltage	V_{IH_FS}	3.3 V +/-5%	0.7		$V_{DD} + 0.3$	V	1
Low Threshold Input-Low Voltage	V_{IL_FS}	3.3 V +/-5%	$V_{SS} - 0.3$		0.35	V	1
Operating Current	$I_{DD3.3OP}$	all outputs driven, CPU@100M			225	mA	1
Powerdown Current	$I_{DD3.3PD}$	WOL_STOP mode (default)			75	mA	1
		all diff pairs driven			30	mA	1
		all differential pairs tri-stated			8	mA	1
Input Frequency	F_i	$V_{DD} = 3.3$ V		25.00		MHz	2
Pin Inductance	L_{pin}				7	nH	1
Input Capacitance	C_{IN}	Logic Inputs			4	pF	1
	C_{OUT}	Output pin capacitance			5	pF	1
	C_{INX}	X1 & X2 pins			5	pF	1
Clk Stabilization	T_{STAB}	From VDD Power-Up or de-assertion of PD to 1st clock		0.5	2.5	ms	1
Modulation Frequency		Triangular Modulation	30		33	kHz	1
Tdrive_PD		CPU output enable after PD de-assertion		260	300	us	1
Tfall_PD		PD fall time of			5	ns	1
Trise_PD		PD rise time of			5	ns	1
SMBus Voltage	V_{DD}		2.7		5.5	V	1
Low-level Output Voltage	V_{OL}	@ I_{PULLUP}			0.4	V	1
Current sinking at $V_{OL} = 0.4$ V	I_{PULLUP}		4	5		mA	1
SCLK/SDATA Clock/Data Rise Time	T_{RI2C}	(Max $V_{IL} - 0.15$) to (Min $V_{IH} + 0.15$)			1000	ns	1
SCLK/SDATA Clock/Data Fall Time	T_{FI2C}	(Min $V_{IH} + 0.15$) to (Max $V_{IL} - 0.15$)			300	ns	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%

¹Guaranteed by design and characterization, not 100% tested in production.

²Input frequency should be measured at the REF pin and tuned to ideal 25.00MHz to meet ppm frequency accuracy on PLL outputs.

Electrical Characteristics–CPU 0.7V Current Mode Differential Pair

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo	VO = Vx	3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal	660	731	850	mV	1,3
Voltage Low	VLow		-150	70	150	mV	1,3
Max Voltage	Vovs	Measurement on single ended signal using absolute value.		800	1150	mV	1
Min Voltage	Vuds		-300	8		mV	1
Crossing Voltage (abs)	Vx(abs)		250	366	550	mV	1
Crossing Voltage (var)	d-Vx	Variation of crossing over all edges		16	140	mV	1
Long Accuracy	ppm	see Tperiod min-max values	-100	0	100	ppm	1,2
Average period	Tperiod	100.00MHz nominal	9.9990	10.0000	10.0001	ns	2
		100.00MHz spread	10.0240	10.0250	10.0251	ns	2
Absolute min/max period	Tabsmn/ max	100.00MHz nominal/spread	9.9490		10.1011	ns	1,2
Rise Time	tr	VOL = 0.175V, VOH = 0.525V	175	376	700	ps	1,4
Fall Time	tf	VOH = 0.525V VOL = 0.175V	175	335	700	ps	1,4
Rise Time Variation	d-tr	VOL = 0.175V, VOH = 0.525V		104	125	ps	1
Fall Time Variation	d-tf	VOH = 0.525V VOL = 0.175V		92	125	ps	1
Rise/Fall Matching	tRFM	Single-ended measurement, averaging on		12.7	20	%	1
Slew Rate	tSLEW	Differential Measurement	1	2	4	V/ns	1,5
Duty Cycle	dt3	Measurement from differential waveform	45	49.8	55	%	1
Jitter, Cycle to cycle	tjcyc-cyc	Measurement from differential waveform, CPUCLK		45	50	ps	1

*T_A = 0 - 70°C; V_{DD} = 3.3 V +/-5%; C_L = 2pF, R_S = 33.2Ω, R_P = 49.9Ω, I_{REF} = 475Ω

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that 25MHz_x is tuned to exactly 25.000MHz

³I_{REF} = V_{DD} / (3xR_R). For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O = 50Ω.

⁴Rise/fall time measured on single-ended waveform per CK410 specification.

⁵Slew rate measured on differential waveform per CK505 specification.

Electrical Characteristics–DOT96SS 0.7V Current Mode Differential Pair

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	Notes
Current Source Output Impedance	Zo	VO = Vx	3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal	660	725	850	mV	1,3
Voltage Low	VLow		-150	51	150	mV	1,3
Max Voltage	Vovs	Measurement on single ended signal using absolute value.		764	1150	mV	1
Min Voltage	Vuds		-300	5		mV	1
Crossing Voltage (abs)	Vx(abs)		250	372	550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Long Accuracy	ppm	see Tperiod min-max values	-100	-41	100	ppm	1,2
Average period	Tperiod	96.00MHz nominal	10.4156	10.4166	10.4176	ns	2
		96.00MHz -0.5% spread	10.4417	10.4427	10.4437	ns	2
Absolute min period	Tabsmmin	96.00MHz nominal/-0.5% spread	10.1917		10.6937	ns	1,2
Rise Time	tr	VOL = 0.175V, VOH = 0.525V	175	361	700	ps	1,4
Fall Time	tf	VOH = 0.525V VOL = 0.175V	175	375	700	ps	1,4
Rise Time Variation	d-tr	VOL = 0.175V, VOH = 0.525V		107	125	ps	1
Fall Time Variation	d-tf	VOH = 0.525V VOL = 0.175V		107	125	ps	1
Rise/Fall Matching	tRFM	Single-ended measurement, averaging on		15	20	%	1
Slew Rate	tSLEW	Differential Measurement	1	2	4	V/ns	1,5
Duty Cycle	dt3	Measurement from differential waveform	45	51.3	55	%	1
Jitter, Cycle to cycle	tjycyc-cyc	Measurement from differential waveform		54	250	ps	1

*TA = 0 - 70°C; VDD = 3.3 V +/-5%; CL = 2pF, RS = 33.2Ω, RP = 49.9Ω, IREF = 475Ω

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that 25MHz_x is tuned to exactly 25.000MHz

³IREF = VDD/(3xRR). For RR = 475Ω (1%), IREF = 2.32mA. IOH = 6 x IREF and VOH = 0.7V @ ZO=50Ω.

⁴Rise/fall time measured on single-ended waveform per CK410 specification.

⁵Slew rate measured on differential waveform per CK505 specification.

Electrical Characteristics–REF - 25MHz

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Long Accuracy	ppm	see Tperiod min-max values	-50	0	50	ppm	1,2
Clock period	Tperiod	25.00MHz output nominal	39.998	40.000	40.002	ns	2
Output High Voltage	VOH	IOH = -1 mA	2.4			V	1
Output Low Voltage	VOL	IOL = 1 mA			0.4	V	1
Output High Current	IOH	VOH@MIN = 1.0 V	-29			mA	1
		VOH@MAX = 3.135 V			-23	mA	1
Output Low Current	IOL	VOL@MIN = 1.95 V	29			mA	1
		VOL@MAX = 0.4 V			27	mA	1
Rise Time	tr1	VOL = 0.4 V, VOH = 2.4 V	0.5	1.14	2	ns	1
Fall Time	tf1	VOH = 2.4 V, VOL = 0.4 V	0.5	1.32	2	ns	1
Skew	tSk1	VT = 1.5 V		16	500	ps	1
Duty Cycle	dt1	VT = 1.5 V	45	53.2	55	%	1
Jitter, Cycle-cycle	tjycyc-cyc	VT = 1.5 V		75	200	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 5 pF with Rs as shown in the termination table (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that 25MHz_x is tuned to exactly 25.000MHz

Electrical Characteristics – RGMII - 125MHz

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-50	0	50	ppm	1,2
Clock period	Tperiod	125.00MHz output nominal	7.9996	8.000	8.0004	ns	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.4	V	1
Output High Current	I _{OH}	V _{OH@MIN} = 1.0 V	-33			mA	1
		V _{OH@MAX} = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL@MIN} = 1.95 V	30			mA	1
		V _{OL@MAX} = 0.4 V			38	mA	1
Rise Time	t _r	V _{OL} =20%×V _{dd} , V _{OH} =80%×V _{dd}		0.66	0.75	ns	1
Fall Time	t _f	V _{OL} =20%×V _{dd} , V _{OH} =80%×V _{dd}		0.70	0.75	ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	45	52.9	55	%	1
Group Skew	t _{skew_RGMII}	V _T = 1.5 V,		15	100	ps	1
Jitter, Long Term	t _{jabs}	V _T = 1.5 V, 10 Ξ sec interval		141	500	ps	1
Jitter, Cycle to cycle	t _{jcy-cyc}	V _T = 1.5 V		75	250	ps	1
Jitter, Peak	t _{jpeak}	V _T = 1.5 V		68	100	ps	1,3

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 5 pF with Rs as shown in the termination table (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that 25MHz_x is tuned to exactly 25.000MHz

³1/2 of the peak-to-peak jitter. (Lg+ + |Lg-|)/2

Electrical Characteristics – RMII - 50MHz

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-50	0	50	ppm	1,2
Clock period	Tperiod	50.00MHz output nominal	19.9990	20.0000	20.001	ns	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.4	V	1
Output High Current	I _{OH}	V _{OH@MIN} = 1.0 V	-33			mA	1
		V _{OH@MAX} = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL@MIN} = 1.95 V	30			mA	1
		V _{OL@MAX} = 0.4 V			38	mA	1
Rise Time	t _r	V _{OL} = 0.4 V, V _{OH} = 2.4 V	0.5	1.1	3	ns	1
Fall Time	t _f	V _{OH} = 2.4 V, V _{OL} = 0.4 V	0.5	1.1	3	ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	35	51.5	65	%	1
Group Skew	t _{skew_RMII(5:0)}	V _T = 1.5 V, across all 6 outputs		60	200	ps	1
Jitter, Long Term	t _{jabs}	V _T = 1.5 V, 10 sec interval		127	500	ps	1
Jitter, Peak	t _{jpeak}	V _T = 1.5 V		88	100	ps	1,3

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 5 pF with Rs as shown in the termination table (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that 25MHz_x is tuned to exactly 25.000MHz

³1/2 of the peak-to-peak jitter. (Lg+ + |Lg-|)/2

Electrical Characteristics–33.33MHz

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-100	0	100	ppm	1
Clock period	Tperiod	33.33MHz output non-spread	29.9970	30.0000	30.0030	ns	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.4	V	1
Output High Current	I _{OH}	V _{OH} @MIN = 1.0 V	-33			mA	1
		V _{OH} @MAX = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL} @ MIN = 1.95 V	30			mA	1
		V _{OL} @ MAX = 0.4 V			38	mA	1
Rise Time	t _r	V _{OL} = 0.4 V, V _{OH} = 2.4 V	0.5	0.87	2	ns	1
Fall Time	t _f	V _{OH} = 2.4 V, V _{OL} = 0.4 V	0.5	1.35	2	ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	45	50.7	55	%	1
Jitter, Cycle to cycle	t _{jcy-cyc}	V _T = 1.5 V		104	350	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 5 pF with Rs as shown in the termination table (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics–32.768KHz

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-100	-79	100	ppm	1
Clock period	Tperiod	32.768KHz output nominal	30.5149	30.5180	30.5211	us	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.4	V	1
Output High Current	I _{OH}	V _{OH} @MIN = 1.0 V	-33			mA	1
		V _{OH} @MAX = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL} @ MIN = 1.95 V	30			mA	1
		V _{OL} @ MAX = 0.4 V			38	mA	1
Rise Time	t _r	V _{OL} = 0.4 V, V _{OH} = 2.4 V	0.5	1.39	4	ns	1
Fall Time	t _f	V _{OH} = 2.4 V, V _{OL} = 0.4 V	0.5	1.6	4	ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	45	49.5	55	%	1
Jitter, Cycle to cycle	t _{jcy-cyc}	V _T = 1.5 V		220	500	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 5 pF with Rs as shown in the termination table (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

General SMBus Serial Interface Information for 9FGP205

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- Renesas clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- Renesas clock will **acknowledge**
- Controller (host) sends the byte count = X
- Renesas clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- Renesas clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- Renesas clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- Renesas clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- Renesas clock will **acknowledge**
- Renesas clock will send the data byte count = X
- Renesas clock sends Byte N+X-1
- Renesas clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Write Operation			
Controller (Host)			(Slave/Receiver)
T	starT bit		
Target Write Address			
WR	WRite		
Beginning Byte = N			ACK
			ACK
Data Byte Count = X			ACK
Beginning Byte N		X Byte	ACK
O			O
O			O
O			O
Byte N + X - 1			ACK
P	stoP bit		

Index Block Read Operation			
Controller (Host)			(Slave/Receiver)
T	starT bit		
Target Write Address			
WR	WRite		
Beginning Byte = N			ACK
			ACK
RT	Repeat starT		
Target Read Address			
RD	ReaD		
			ACK
ACK		X Byte	Data Byte Count=X
ACK			Beginning Byte N
O			O
O			O
O			O
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

The SMBus address depends on the latched value of pin 22. Please see SMBus Address Selection table on page 1.

SMBus Table: CPU Frequency Select and Spread Spectrum Control Register

Byte 0	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	WOL_STOP_EN	Enables 25M in Power Down	RW	Disable	Enabled	1
Bit 6	-	Reserved	Reserved	RW	Reserved		0
Bit 5	-	Reserved	Reserved	RW	Reserved		0
Bit 4	-	DOT96_SS_EN	DOT96 Spread Spectrum Enable	RW	Disable	Enable	0
Bit 3	-	CPU_SS_EN	CPU Spread Spectrum Enable	RW	See Table 1: CPU Frequency Selection Table		0
Bit 2	-	CPU_FS2	CPU Freq Select Bit 2	RW			1
Bit 1	-	CPU_FS1	CPU Freq Select Bit 1	RW			0
Bit 0	-	CPU_FS0	CPU Freq Select Bit 0	RW			1

SMBus Table: RMII Output Control Register

Byte 1	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	24	RMII_5 Enable	RMII_7 Output Control	RW	Disable	Enable	1
Bit 6	25	1.8	RMII_6 Output Control	RW	Disable	Enable	1
Bit 5	28	RMII_3 Enable	RMII_5 Output Control	1.4	Disable	Enable	1
Bit 4	29	RMII_2 Enable	RMII_4 Output Control	RW	Disable	Enable	1
Bit 3	32	RMII_1 Enable	RMII_3 Output Control	RW	Disable	Enable	1
Bit 2	33	RMII_0 Enable	RMII_2 Output Control	RW	Disable	Enable	1
Bit 1	36	RGMII_1 Enable	RGMII_1 Output Control	RW	Disable	Enable	1
Bit 0	37	RGMII_0 Enable	RGMII_0 Output Control	RW	Disable	Enable	1

SMBus Table: DOT, CPU, 32.768KHz, 25MHz and 33.33MHz Outputs Control Register

Byte 2	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	7,8	CPUCLK_PD Drive Mode	Driven in power down	RW	Driven	Hi-Z	1
Bit 6	3,4	DOT96SS_PD Drive Mode	Driven in power down	RW	Driven	Hi-Z	1
Bit 5	22	33.33MHz Enable	33.33MHz Output Control	RW	Disable	Enable	1
Bit 4	17	25MHz_1 Enable	25MHz_1 Output Control	RW	Disable	Enable	1
Bit 3	16	25MHz_0 Enable	25MHz_0 Output Control	RW	Disable	Enable	1
Bit 2	13	32.768kHz Enable	32.768kHz Output Control	RW	Disable	Enable	1
Bit 1	6	CPUCLK Enable	CPUCLK Output Control	RW	Disable	Enable	1
Bit 0	5	DOT96SS Enable	DOT96SS Output Control	RW	Disable	Enable	1

SMBus Table: DOT96 Frequency Select and Spread Spectrum Control Register

Byte 3	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	24	RMII_5 WOL_STOP	RMII_5 runs in power down	RW	Off	Runs	0
Bit 6	25	RMII_4 WOL_STOP	RMII_4 runs in power down	RW	Off	Runs	0
Bit 5	28	RMII_3 WOL_STOP	RMII_3 runs in power down	RW	Off	Runs	0
Bit 4	29	RMII_2 WOL_STOP	RMII_2 runs in power down	RW	Off	Runs	1
Bit 3	-	DOT96SS_FS3	DOT96 Freq Select Bit 3	RW	See Table 2: DOT Frequency Selection Table		0
Bit 2	-	DOT96SS_FS2	DOT96 Freq Select Bit 2	RW			0
Bit 1	-	DOT96SS_FS1	DOT96 Freq Select Bit 1	RW			0
Bit 0	-	DOT96SS_FS0	DOT96 Freq Select Bit 0	RW			0

SMBus Table: RMII Strength Control Register

Byte 4	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	24	RMII_5 Str	RMII_5 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 6	25	RMII_4 Str	RMII_4 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 5	28	RMII_3 Str	RMII_3 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 4	29	RMII_2 Str	RMII_2 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 3	32	RMII_1 Str	RMII_1 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 2	33	RMII_0 Str	RMII_0 Strength Control	RW	1-Load (1X)	2-Loads (2X)	0
Bit 1	32	RMII_1 WOL_STOP	RMII_1 runs in power down	RW	Off	Runs	1
Bit 0	33	RMII_0 WOL_STOP	RMII_0 runs in power down	RW	Off	Runs	1

SMBus Table: 32.768KHz, 25MHz and 33.33MHz Strength Control Register

Byte 5	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	Reserved	Reserved	RW	Reserved		0
Bit 6	-	Reserved	Reserved	RW	Reserved		0
Bit 5	22	33.33MHz Str	33.33MHz Strength Control	RW	1-Load (1X)	2-Loads (2X)	1
Bit 4	17	25MHz_1 Str	25MHz_1 Strength Control	RW	1-Load (1X)	2-Loads (2X)	1
Bit 3	16	25MHz_0 Str	25MHz_1 Strength Control	RW	1-Load (1X)	2-Loads (2X)	1
Bit 2	13	32.768kHz Str	32.768kHz Strength Control	RW	1-Load (1X)	2-Loads (2X)	1
Bit 1	17	25MHz_1 WOL_STOP	25MHz_1 runs in power down	RW	Off	Runs	0
Bit 0	16	25MHz_0 WOL_STOP	25MHz_0 runs in power down	RW	Off	Runs	1

SMBus Table: Vendor & Revision ID Register

Byte 6	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	RID3	REVISION ID	R	A rev = 0000 B rev = 0001		X
Bit 6	-	RID2		R			X
Bit 5	-	RID1		R			X
Bit 4	-	RID0		R			X
Bit 3	-	VID3	VENDOR ID	R	ICS/IDT = 0001		0
Bit 2	-	VID2		R			0
Bit 1	-	VID1		R			0
Bit 0	-	VID0		R			1

SMBus Table: Device ID

Byte 7	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	Device ID 7 (MSB)	Device ID	R	Reserved		0
Bit 6	-	Device ID 6		R	Reserved		0
Bit 5	-	Device ID 5		R	Reserved		1
Bit 4	-	Device ID 4		R	Reserved		0
Bit 3	-	Device ID 3		R	Reserved		0
Bit 2	-	Device ID 2		R	Reserved		1
Bit 1	-	Device ID 1		R	Reserved		0
Bit 0	-	Device ID 0 (LSB)		R	Reserved		1

SMBus Table: Byte Count Register

Byte 8	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	BC7	Writing to this register configures how many bytes will be read back.	RW	-	-	0
Bit 6	-	BC6		RW	-	-	0
Bit 5	-	BC5		RW	-	-	0
Bit 4	-	BC4		RW	-	-	0
Bit 3	-	BC3		RW	-	-	1
Bit 2	-	BC2		RW	-	-	0
Bit 1	-	BC1		RW	-	-	0
Bit 0	-	BC0		RW	-	-	1

SMBus Table: Reserved

Byte 9	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

SMBus Table: PLLs M/N Programming Enable Register

Byte 10	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	M/N_EN	PLLs M/N Programming Enable	RW	Disable	Enable	0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0

SMBus Table: CPU PLL VCO Frequency Control Register

Byte 11	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divier in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = 14.318 x		X
Bit 6	-	N Div 9	N Divider Prog bit 9	RW			X
Bit 5	-	M Div5	M Divider Programming bits	RW			X
Bit 4	-	M Div4		RW			X
Bit 3	-	M Div3		RW			X
Bit 2	-	M Div2		RW			X
Bit 1	-	M Div1		RW			X
Bit 0	-	M Div0		RW			X

SMBus Table: CPU PLL VCO Frequency Control Register

Byte 12	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	N Div7	N Divider Programming b(7:0)	RW	The decimal representation of M and N Divier in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = 14.318 x		X
Bit 6	-	N Div6		RW			X
Bit 5	-	N Div5		RW			X
Bit 4	-	N Div4		RW			X
Bit 3	-	N Div3		RW			X
Bit 2	-	N Div2		RW			X
Bit 1	-	N Div1		RW			X
Bit 0	-	0.5		RW			X

0.5

SMBus Table: CPU PLL Spread Spectrum Control Register

Byte 13	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	SSP7	Spread Spectrum Programming b(7:0)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 6	-	SSP6		RW			X
Bit 5	-	SSP5		RW			X
Bit 4	-	SSP4		RW			X
Bit 3	-	SSP3		RW			X
Bit 2	-	SSP2		RW			X
Bit 1	-	SSP1		RW			X
Bit 0	-	SSP0		RW			X

SMBus Table: CPU PLL Spread Spectrum Control Register

Byte 14	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7			Reserved				0
Bit 6	-	SSP14	Spread Spectrum Programming b(14:8)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 5	-	SSP13		RW			X
Bit 4	-	SSP12		RW			X
Bit 3	-	SSP11		RW			X
Bit 2	-	SSP10		RW			X
Bit 1	-	SSP9		RW			X
Bit 0	-	SSP8		RW			X

SMBus Table: DOT PLL VCO Frequency Control Register

Byte 15	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divier in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = $14.318 \times [\text{NDiv}(9:0)+8] /$		X
Bit 6	-	N Div9	N Divider Prog bit 9	RW			X
Bit 5	-	M Div5	M Divider Programming bits	RW			X
Bit 4	-	M Div4		RW			X
Bit 3	-	M Div3		RW			X
Bit 2	-	M Div2		RW			X
Bit 1	-	M Div1		RW			X
Bit 0	-	M Div0		RW			X

SMBus Table: DOT PLL VCO Frequency Control Register

Byte 16	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	N Div7	N Divider Programming b(7:0)	RW	The decimal representation of M and N Divier in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = $14.318 \times [\text{NDiv}(9:0)+8] /$		X
Bit 6	-	N Div6		RW			X
Bit 5	-	N Div5		RW			X
Bit 4	-	N Div4		RW			X
Bit 3	-	N Div3		RW			X
Bit 2	-	0.5		RW			X
Bit 1	-	0.5		RW			X
Bit 0	-	N Div0		RW			X

SMBus Table: DOT PLL Spread Spectrum Control Register

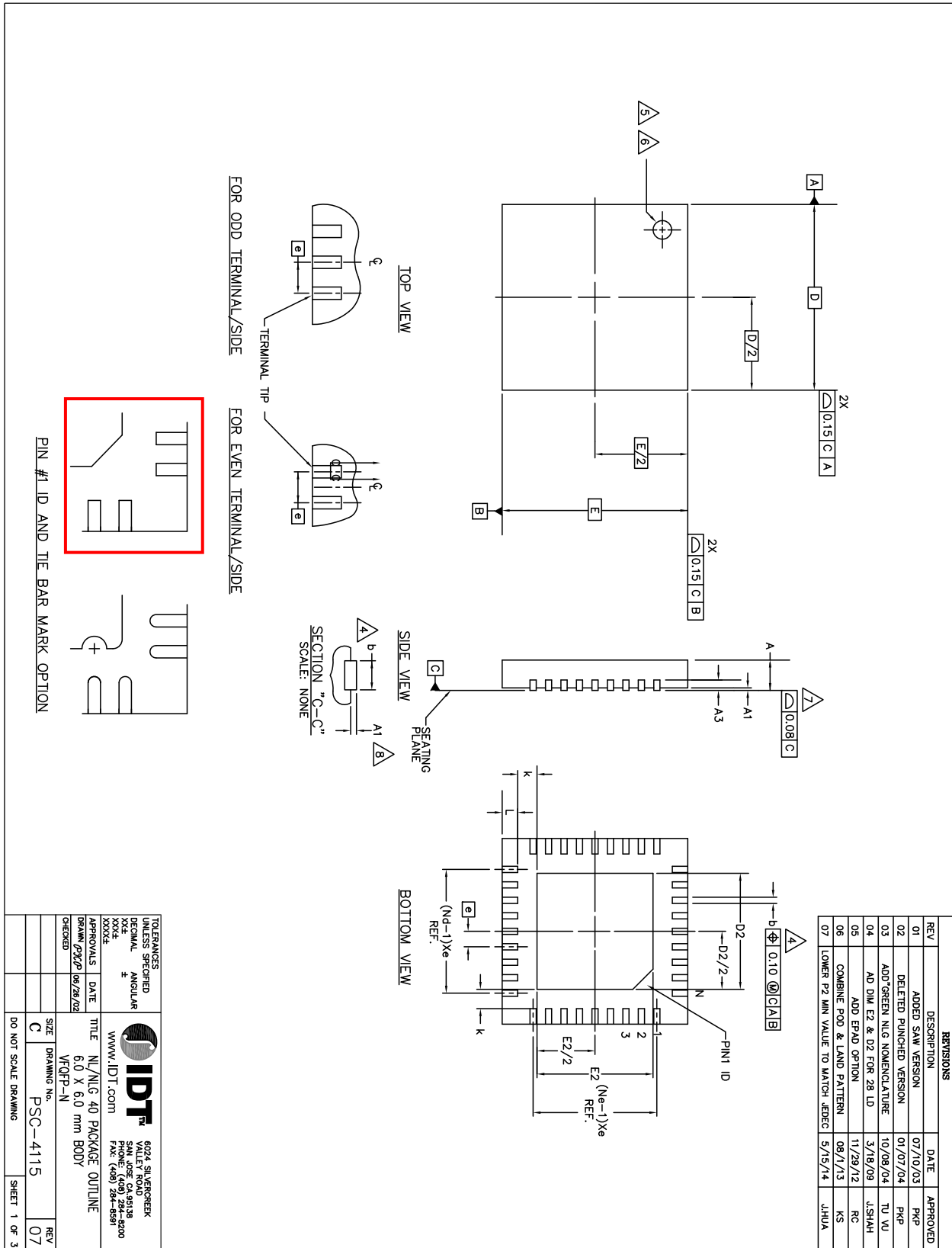
Byte 17	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	SSP7	Spread Spectrum Programming b(7:0)	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 6	-	SSP6		RW			X
Bit 5	-	SSP5		RW			X
Bit 4	-	SSP4		RW			X
Bit 3	-	SSP3		RW			X
Bit 2	-	SSP2		RW			X
Bit 1	-	SSP1		RW			X
Bit 0	-	SSP0		RW			X

SMBus Table: DOT PLL Spread Spectrum Control Register

Byte 18	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		Reserved				0
Bit 6	-	SSP14	Spread Spectrum Programming b(14:8)	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 5	-	0.5		RW			X
Bit 4	-	0.5		RW			X
Bit 3	-	SSP11		RW			X
Bit 2	-	SSP10		RW			X
Bit 1	-	SSP9		RW			X
Bit 0	-	SSP8		RW			X

Bytes 19:21 are reserved.

Package Outline and Dimensions (NLG40)



Package Outline and Dimensions (NLG40), cont. Use EPAD option P1

EPAD OPTION:

SYMBOL	P1			P2		
	MIN	NOM	MAX	MIN	NOM	MAX
D2	2.80	2.90	3.00	4.50	4.65	4.75
E2	2.80	2.90	3.00	4.50	4.65	4.75

NOTES:

1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M. – 1994.
2. N IS THE NUMBER OF TERMINALS.
ND IS THE NUMBER OF TERMINALS IN X-DIRECTION &
Ne IS THE NUMBER OF TERMINALS IN Y-DIRECTION.
3. ALL DIMENSIONS ARE IN MILLIMETERS.
4. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.30mm FROM TERMINAL TIP.
5. THE PIN #1 IDENTIFIER MUST EXIST ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. APPLIED TO EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDED PART OF EXPOSED PAD FROM MEASURING.
8. APPLIED ONLY FOR TERMINALS.
9. THIS OUTLINES CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-220, VARIATION VJUC-3 & VJUD-5 WITH THE EXCEPTION OF D2 & E2.

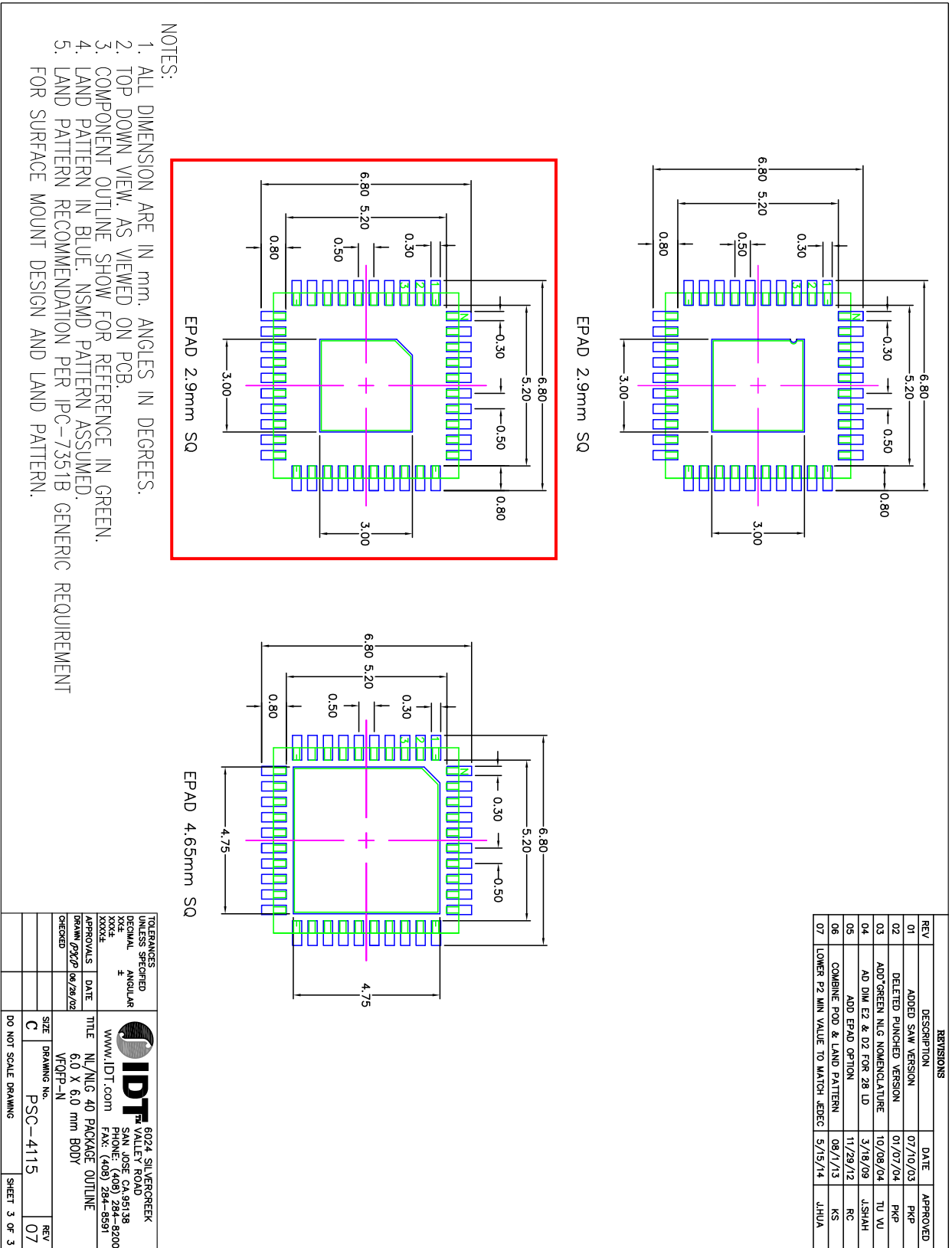
COMMON DIMENSION

SYMBOL	DIMENSION			NOTE
	MIN	NOM	MAX	
b	0.18	0.25	0.30	4
D	6.00 BSC			
E	6.00 BSC			
D2	SEE EPAD OPTION			
E2	SEE EPAD OPTION			
L	0.30	0.40	0.50	
e	0.50 BSC			
N	40			2
A	0.80	0.90	1.00	
A1	0.00	0.02	0.05	7
A3	0.2 REF			
ND	10			2
Ne	10			2

REVISIONS				
REV	DESCRIPTION	DATE	APPROVED	
01	ADDED SAW VERSION	07/10/03	PRP	
02	DELETED PUNCHING VERSION	01/07/04	PRP	
03	ADDFREEN NLS NOMENCLATURE	10/08/04	TU YU	
04	AD DIM E2 & D2 FOR 28 LD	3/18/08	JISHIH	
05	ADD EPAD OPTION	11/29/12	RC	
06	COMBINE PAD & LAND PATTERN	08/1/13	KS	
07	LOWER P2 MIN VALUE TO MATCH JEDEC	5/15/14	JHUA	

UNLESS SPECIFIED DIMENSIONAL TOLERANCES ARE ANGULAR		6024 SILVERCREEK VALLEJO, CA 94588 PHONE: (408) 284-8200 FAX: (408) 284-8591
APPROVALS		WWW.IDT.COM
DRAWN	TITLE	6.0 X 6.0 mm BODY
CHECKED	DATE	VFOFP-N
SIZE	DRAWING NO.	PSC-4115
DO NOT SCALE DRAWING		SHEET 2 OF 3

Package Outline and Dimensions (NLG40), cont.



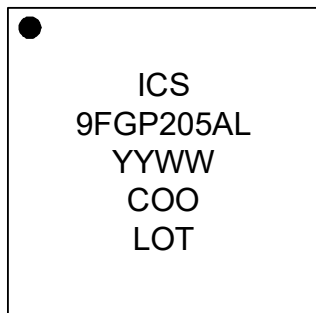
Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature	MOQ
9FGP205AKLF	Trays	40-pin VFQFPN	0 to +70° C	490
9FGP205AKLFT	Tape and Reel	40-pin VFQFPN	0 to +70° C	5000
9FGP205AKLFT-1K	Tape and Reel	40-pin VFQFPN	0 to +70° C	1000

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

Marking Diagram



Notes:

1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. "YYWW" is the last two digits of the year and week that the part was assembled.
4. "L" denotes RoHS compliant package.

Revision History

Revision Date	Description
3/11/2015	Initial release
3/31/2026	Updated General SMBus instructions and Index Block tables.

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TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
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